

N-CHANNEL SILICON POWER MOS-FET**F-III SERIES****■ Features**

- High current
- Low no-resistance
- No secondary breakdown
- Low driving power
- High forward Transconductance

■ Applications

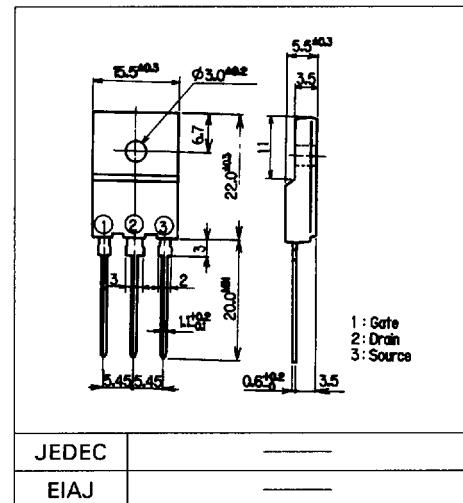
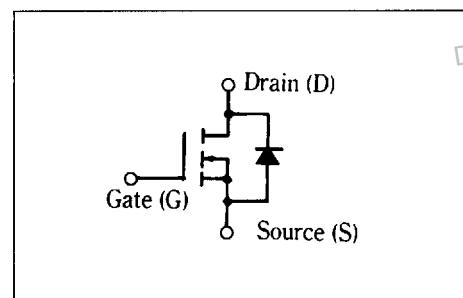
- Motor controllers
- General purpose power amplifier
- DC-DC converters

■ Max. Ratings and Characteristics**● Absolute Maximum Ratings($T_c=25^\circ\text{C}$)**

Items	Symbols	Ratings	Units
Drain-source voltage	V_{DSS}	60	V
Continuous drain current	I_D	35	A
Pulsed drain current	$I_{D(\text{puls})}$	140	A
Continuous reverse drain current	I_{DR}	35	A
Gate-source peak voltage	V_{GSS}	± 20	V
Max. power dissipation	P_D	50	W
Operating and storage temperature range	T_{ch}	150	$^\circ\text{C}$
	T_{stg}	-55 ~ +150	$^\circ\text{C}$

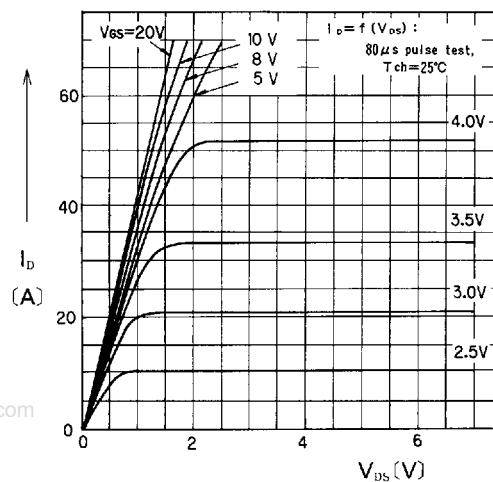
● Electrical Characteristics($T_c=25^\circ\text{C}$)

Items	Symbols	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1\text{mA}$ $V_{GS} = 0\text{V}$	60			V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D = 1\text{mA}$ $V_{DS} = V_{GS}$	1.0	1.5	2.5	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 60\text{V}$ $T_{ch} = 25^\circ\text{C}$ $V_{GS} = 0\text{V}$ $T_{ch} = 125^\circ\text{C}$		10	500	μA
Gate-source leakage current	I_{GSS}	$V_{GS} = \pm 20\text{V}$ $V_{DS} = 0\text{V}$		10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 17.5\text{A}$ $V_{GS} = 4\text{V}$		37	56	$\text{m}\Omega$
		$I_D = 17.5\text{A}$ $V_{GS} = 10\text{V}$		25	35	$\text{m}\Omega$
Forward transconductance	g_{fs}	$I_D = 17.5\text{A}$ $V_{DS} = 25\text{V}$	10	18		S
Input capacitance	C_{iss}	$V_{DS} = 25\text{V}$		1800	2700	pF
Output capacitance	C_{oss}	$V_{GS} = 0\text{V}$		620	930	
Reverse transfer capacitance	C_{rss}	$f = 1\text{MHz}$		240	360	
Turn-on time t_{on} ($t_{on} = t_{d(on)} + t_r$)	$t_{d(on)}$ t_r	$V_{CC} = 30\text{V}$ $I_D = 35\text{A}$		6 60	9 90	ns
Turn-off time t_{off} ($t_{off} = t_{d(off)} + t_f$)	$t_{d(off)}$ t_f	$V_{GS} = 10\text{V}$ $R_G = 25\Omega$		350	530	
				150	230	
Diode forward on-voltage	V_{SD}	$I_F = 2 \times I_{DR}$ $V_{GS} = 0\text{V}$ $T_{ch} = 25^\circ\text{C}$		1.35	2.0	V
Reverse recovery time	t_{rr}	$I_F = I_{DR}$ $d_I/d_t = 100\text{A}/\mu\text{s}$ $T_{ch} = 25^\circ\text{C}$		60		ns

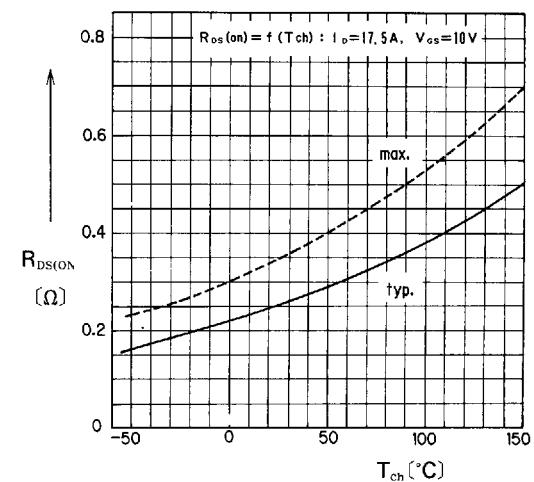
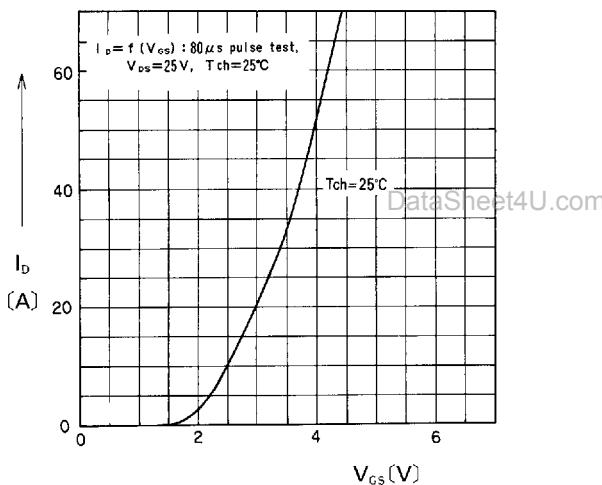
■ Outline Drawings**■ Equivalent Circuit Schematic****● Thermal Characteristics**

Items	Symbols	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	$R_{th(ch-a)}$ $R_{th(ch-c)}$	channel to air channel to case			30.0 3.125	$^\circ\text{C}/\text{W}$

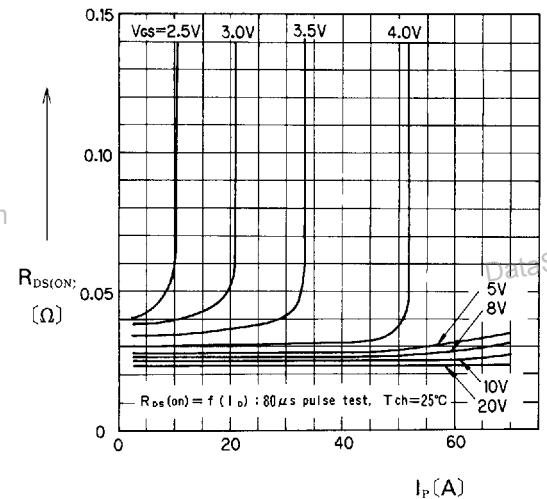
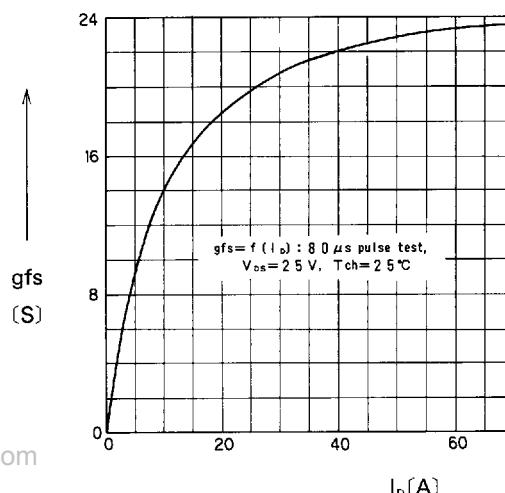
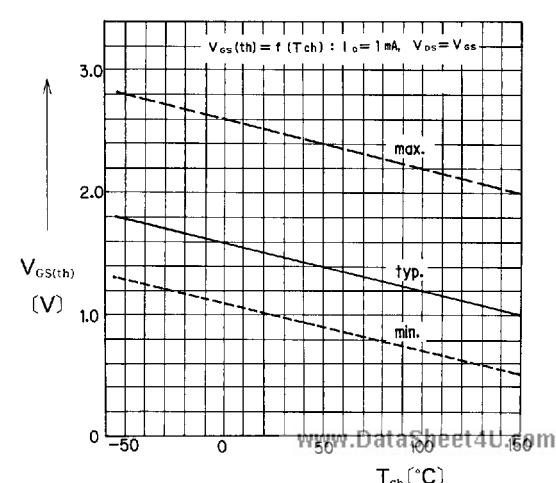
■ Characteristics

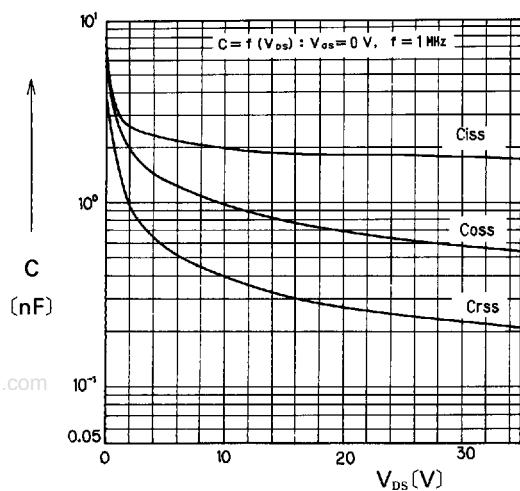
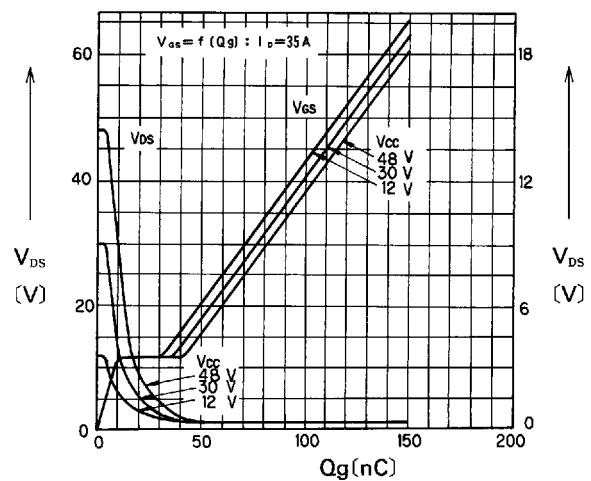


Typical Output Characteristics

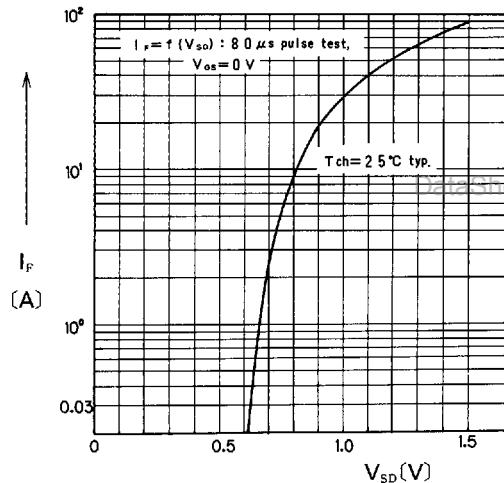
On State Resistance vs. T_{ch} 

Typical Transfer Characteristics

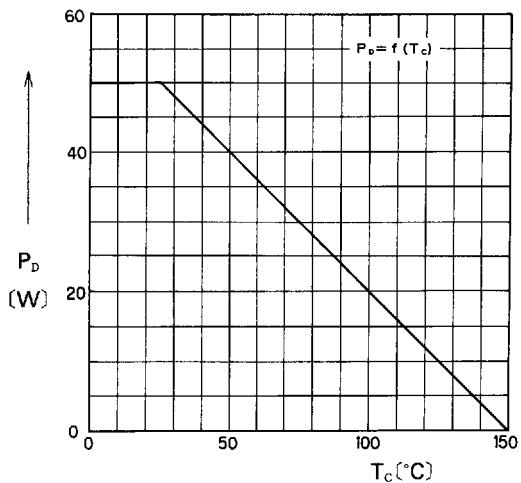
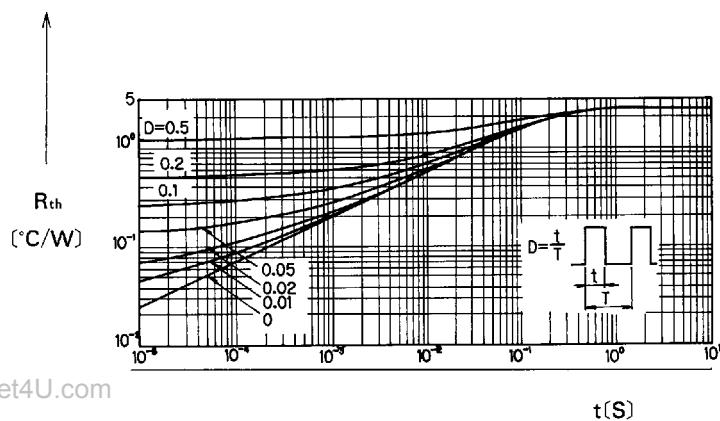
Typical Drain-Source on State Resistance vs. I_D Typical Forward Transconductance vs. I_D Gate Threshold Voltage vs. T_{ch}

Typical Capacitance vs. V_{DS} 

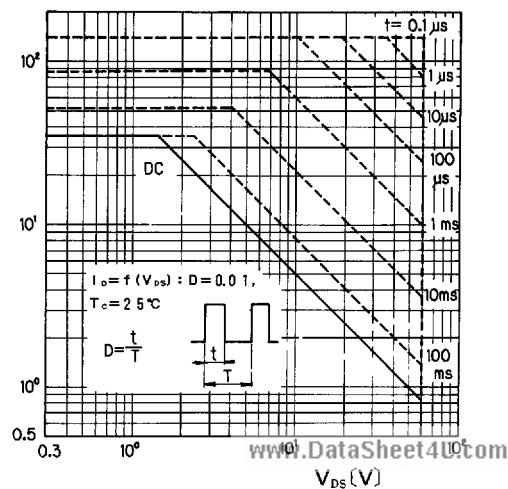
Typical Input Charge



Forward Characteristics of Reverse Diode

Allowable Power Dissipation vs. T_c 

Transient Thermal Impedance



Safe Operating Area